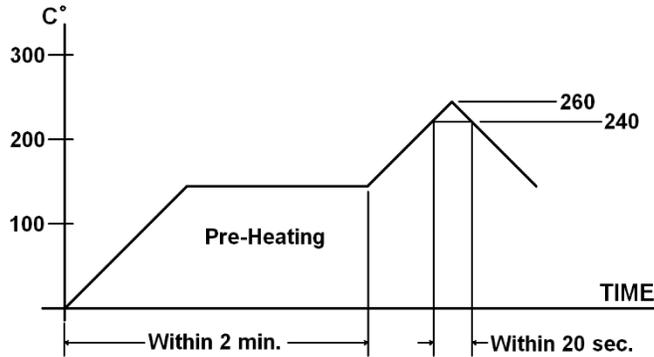


CIT Relay & Switch Soldering Guideline – Relay

Guidelines for soldering and cleaning CIT Relay products.

SMT Temperature Profile:



Guidelines for wave soldering: CIT Relay & Switch recommends using a rosin-based, no-corrosive flux during any wave soldering process. The terminal area on most CIT Relay & Switch product is epoxy sealed, thus preventing flux from wicking into the inner relay cavity via the terminals. The position of the PC board should be adjusted so that flux does not overflow the top of the board. This is especially important when using unsealed relays as they are more susceptible to contamination from flux overflow. Good venting is also required during the wave soldering process. Flux vapors can contaminate unsealed relays by condensing on critical components including the contact area. Sealed relays can safely be cleaned by immersion, but should be cooled to room temperature before beginning the process. Unsealed relays should not be cleaned by immersion at any time.

Preheat Temperature & Time: Circumferential temperature of the PC board not to exceed 100°C (212°F) for 60 seconds.

Soldering Temperature & Time: Solder bath temperature not to exceed 260°C (482°F) for 5 seconds.

Guidelines for Hand Soldering: CIT Relay & Switch recommends using a rosin-based flux during any hand soldering process.

Hand Soldering Temperature & Time: Recommended soldering irons not to exceed 60W. Suggested soldering temperature is 350°C. Solder and iron should contact terminals for a maximum of 5 seconds.

